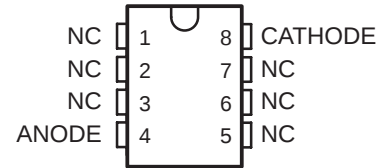


LM285-2.5, LM385-2.5, LM385B-2.5 MICROPOWER VOLTAGE REFERENCES

SLVS023J – JANUARY 1989 – REVISED MARCH 2005

- Operating Current Range . . . 20 μ A to 20 mA
- 1.5% and 3% Initial Voltage Tolerance
- Reference Impedance
 - LM385 . . . 1 Ω Max at 25°C
 - All Devices . . . 1.5 Ω Max Over Full Temperature Range
- Very Low Power Consumption
- Applications
 - Portable Meter References
 - Portable Test Instruments
 - Battery-Operated Systems
 - Current-Loop Instrumentation
 - Panel Meters
- Interchangeable With Industry-Standard LM285-2.5 and LM385-2.5

LM285-2.5 . . . D PACKAGE
LM385-2.5, LM385B-2.5 . . . D OR PW PACKAGE
(TOP VIEW)



NC – No internal connection

LM285-2.5, LM385-2.5, LM385B-2.5 . . . LP PACKAGE
(TOP VIEW)



NC – No internal connection

description/ordering information

These micropower two-terminal band-gap voltage references operate over a 20- μ A to 20-mA current range and feature exceptionally low dynamic impedance and good temperature stability. On-chip trimming provides tight voltage tolerance. The band-gap reference for these devices has low noise and long-term stability.

ORDERING INFORMATION

T _A	V _Z TOLERANCE	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	3%	SOIC (D)	Tube of 75	LM385D-2-5	385-25
			Reel of 2000	LM385DR-2-5	
		TO226/TO-92 (LP)	Tube of 1000	LM385LP-2-5	385-25
			Reel of 2000	LM385LPR-2-5	
		TSSOP (PW)	Tube of 150	LM385PW-2-5	385-25
			Reel of 2000	LM385PWR-2-5	
	1.5%	SOIC (D)	Tube of 75	LM385BD-2-5	385B25
			Reel of 2000	LM385BDR-2-5	
		TO226/TO-92 (LP)	Tube of 1000	LM385BLP-2-5	385-25
			Reel of 2000	LM385BLPR-2-5	
TSSOP (PW)		Tube of 150	LM385BPW-2-5	385B25	
		Reel of 2000	LM385BPWR-2-5		
−40°C to 85°C	1.5%	SOIC (D)	Tube of 75	LM285D-2-5	285-25
			Reel of 2000	LM285DR-2-5	
		TO226/TO-92 (LP)	Tube of 1000	LM285LP-2-5	285-25
			Reel of 2000	LM285LPR-2-5	285-25

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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LM285-2.5, LM385-2.5, LM385B-2.5 MICROPOWER VOLTAGE REFERENCES

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description/ordering information (continued)

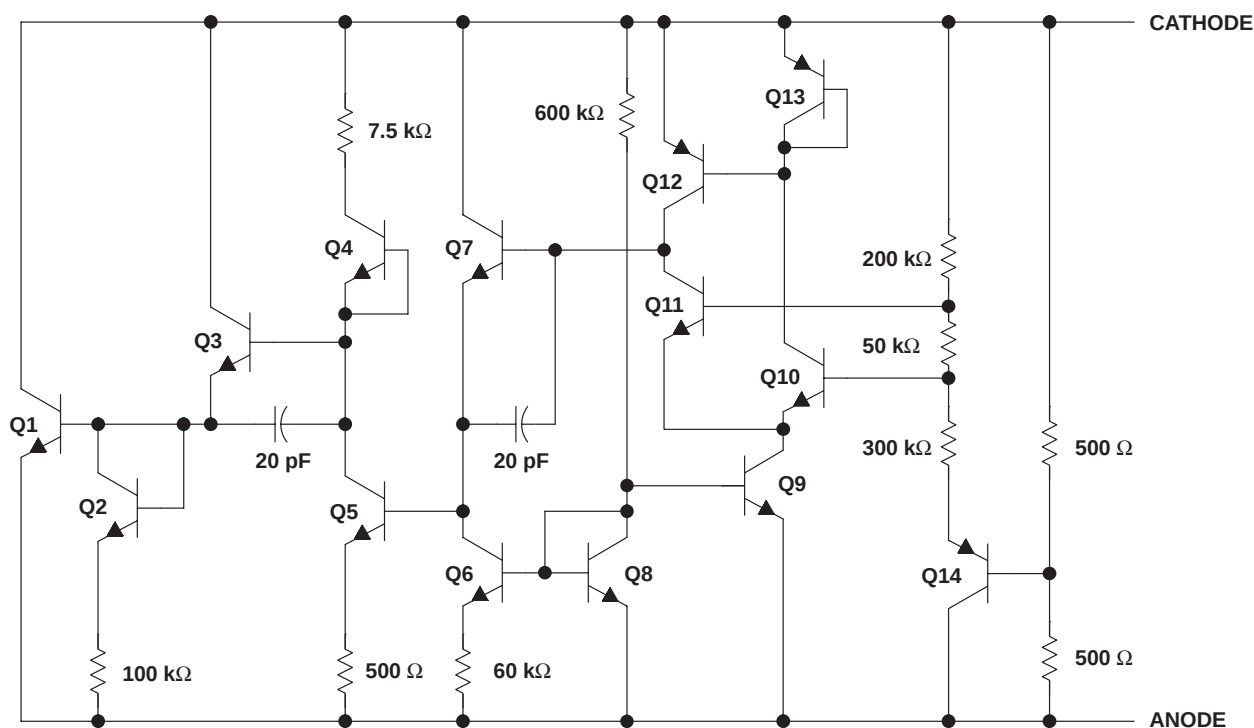
The design makes these devices exceptionally tolerant of capacitive loading and, thus, easier to use in most reference applications. The wide dynamic operating temperature range accommodates varying current supplies, with excellent regulation.

The extremely low power drain of this series makes them useful for micropower circuitry. These voltage references can be used to make portable meters, regulators, or general-purpose analog circuitry, with battery life approaching shelf life. The wide operating current range allows them to replace older references with tighter-tolerance parts.

symbol



schematic



NOTE A: All component values shown are nominal.

LM285-2.5, LM385-2.5, LM385B-2.5 MICROPOWER VOLTAGE REFERENCES

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Reverse current, I_R	30 mA
Forward current, I_F	10 mA
Package thermal impedance, θ_{JA} (see Notes 1 and 2): D package	97°C/W
LP package	140°C/W
PW package	149°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. Maximum power dissipation is a function of $T_{J(max)}$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_{J(max)} - T_A)/\theta_{JA}$. Operation at the absolute maximum T_J of 150°C can affect reliability.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

		MIN	MAX	UNIT
I_Z	Reference current	0.02	20	mA
T_A	Operating free-air temperature range	LM285-2.5	–40	85
		LM385-2.5, LM385B-2.5	0	70

electrical characteristics at specified free-air temperature

PARAMETER		TEST CONDITIONS	T _A [‡]	LM285-2.5			LM385-2.5			LM385B-2.5			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
V _Z	Reference voltage	I _Z = 20 μA to 20 mA	25°C	2.462	2.5	2.538	2.425	2.5	2.575	2.462	2.5	2.538	V
α _{VZ}	Average temperature coefficient of reference voltage [§]	I _Z = 20 μA to 20 mA	Full range	±20			±20			±20			ppm/°C
ΔV _Z	Change in reference voltage with current	I _Z = 20 μA to 1 mA	25°C	1			2			2			mV
			Full range	1.5			2			2			
		I _Z = 1 mA to 20 mA	25°C	10			20			20			
			Full range	30			30			30			
ΔV _Z /Δt	Long-term change in reference voltage	I _Z = 100 μA	25°C	±20			±20			±20			ppm/khr
I _Z (min)	Minimum reference current		Full range	8 20			8 20			8 20			μA
z _Z	Reference impedance	I _Z = 100 μA	25°C	0.2 0.6			0.4 1			0.4 1			Ω
			Full range	1.5			1.5			1.5			
V _n	Broadband noise voltage	I _Z = 100 μA, f = 10 Hz to 10 kHz	25°C	120			120			120			μV

[‡] Full range is 0°C to 70°C for the LM385-2.5 and LM385B-2.5, and –40°C to 85°C for the LM285-2.5.

[§] The average temperature coefficient of reference voltage is defined as the total change in reference voltage divided by the specified temperature range.



LM285-2.5, LM385-2.5, LM385B-2.5 MICROPOWER VOLTAGE REFERENCES

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TYPICAL CHARACTERISTICS†

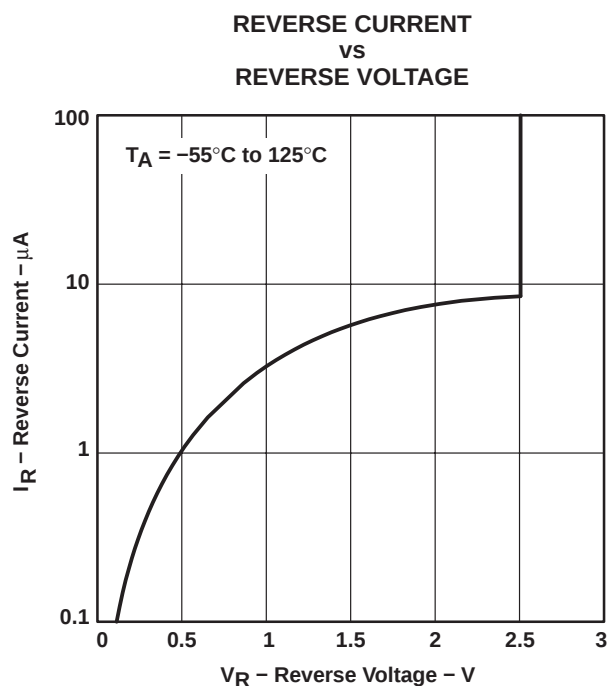


Figure 1

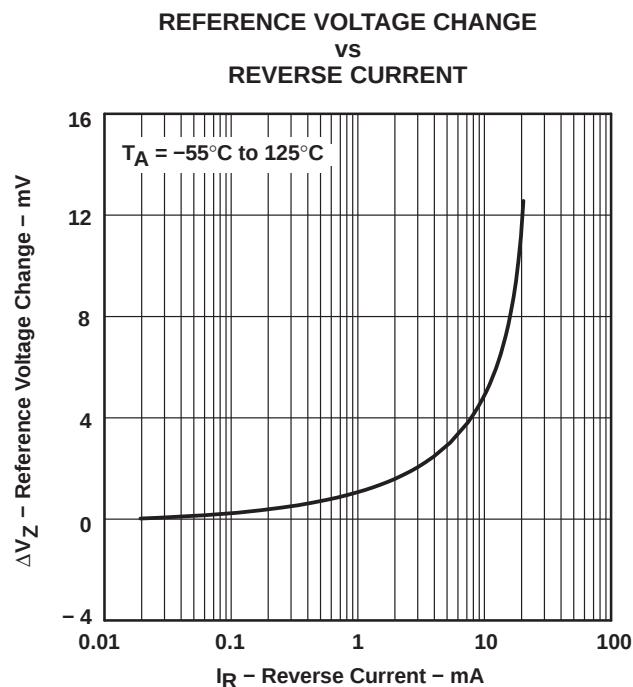


Figure 2

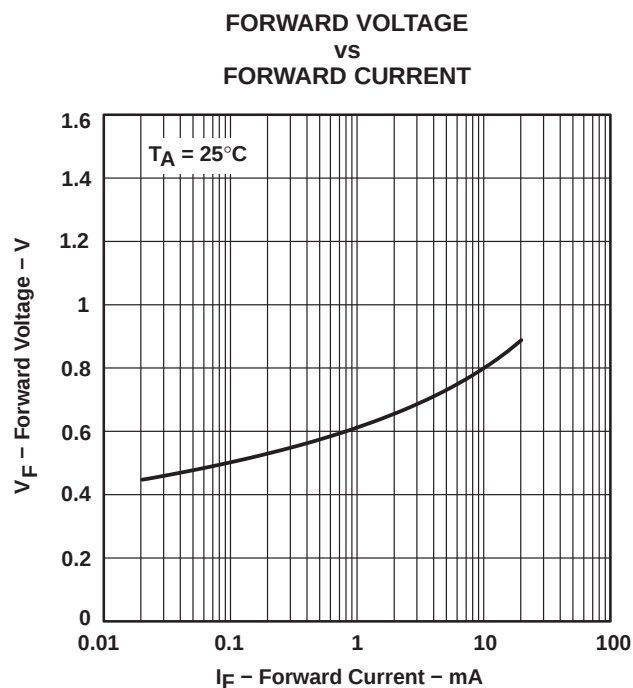


Figure 3

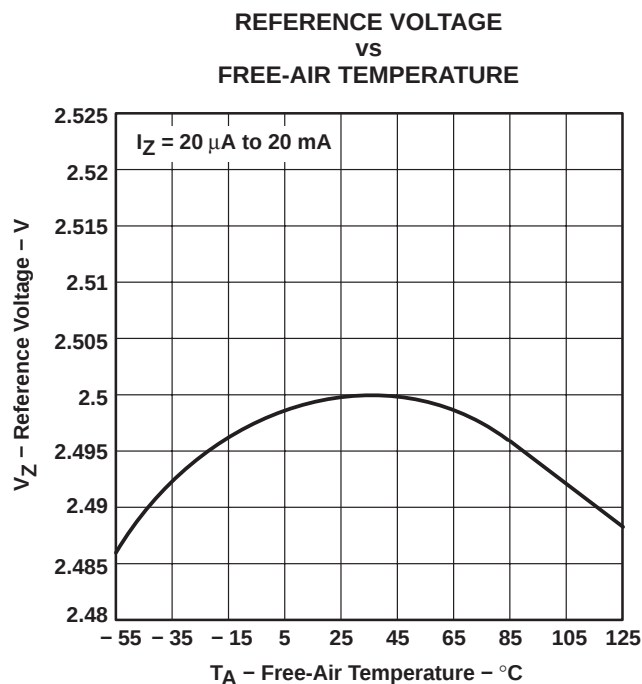


Figure 4

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS†

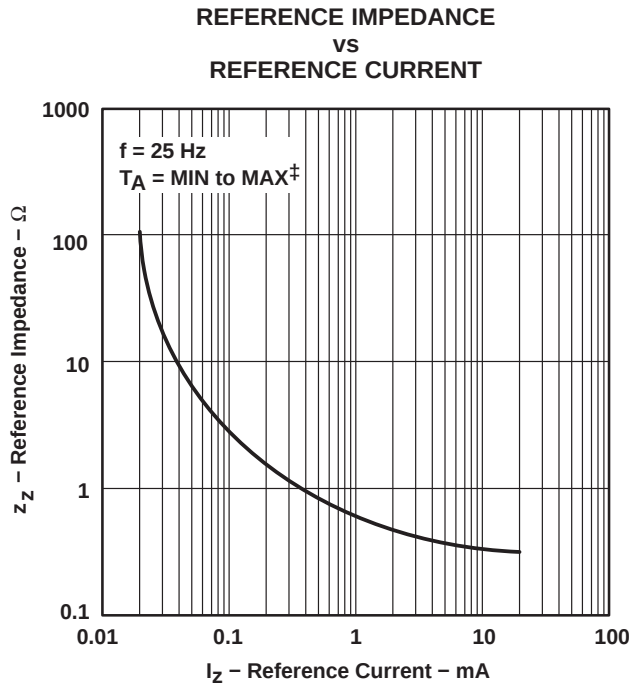


Figure 5

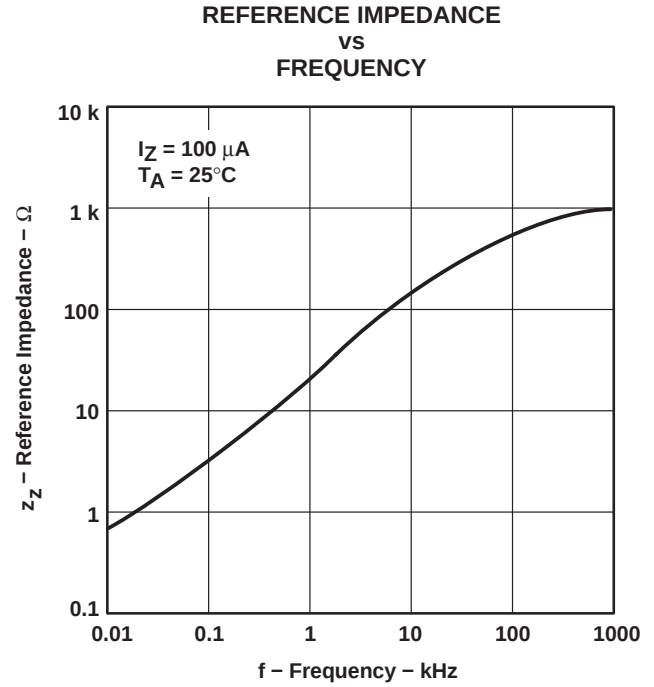


Figure 6

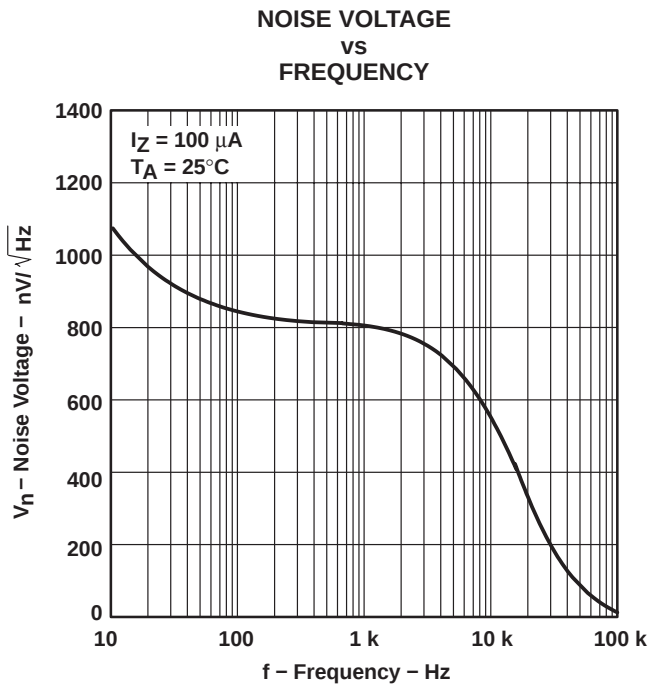


Figure 7

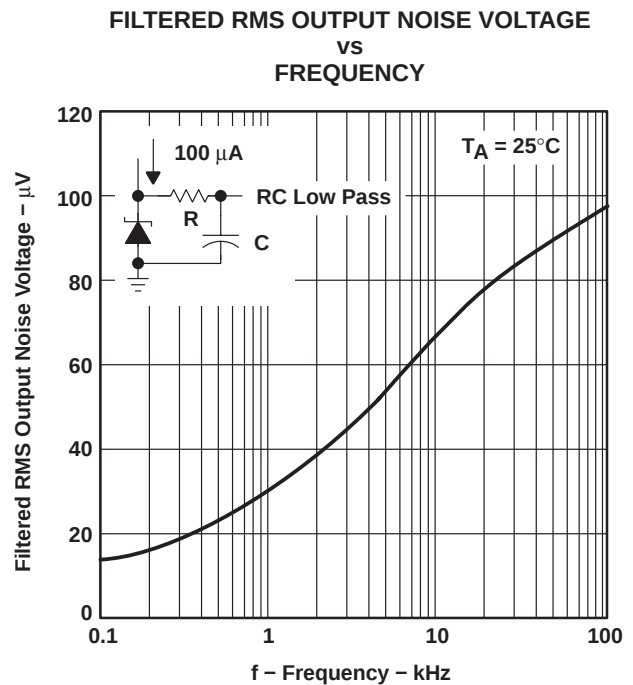


Figure 8

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

‡ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

LM285-2.5, LM385-2.5, LM385B-2.5 MICROPOWER VOLTAGE REFERENCES

SLVS023J – JANUARY 1989 – REVISED MARCH 2005

TYPICAL CHARACTERISTICS[†]

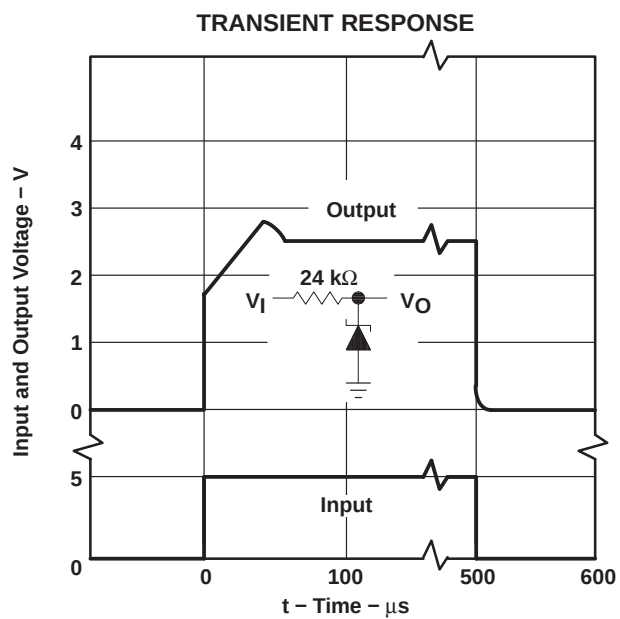
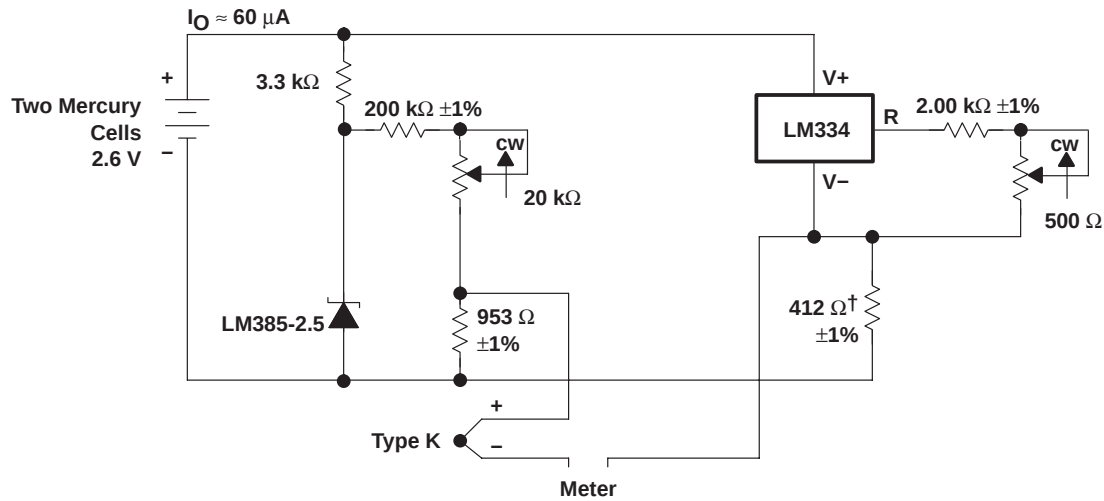


Figure 9

[†] Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

APPLICATION INFORMATION



† Adjust for 12.17 mV at 25°C across 412 Ω

Figure 10. Thermocouple Cold-Junction Compensator

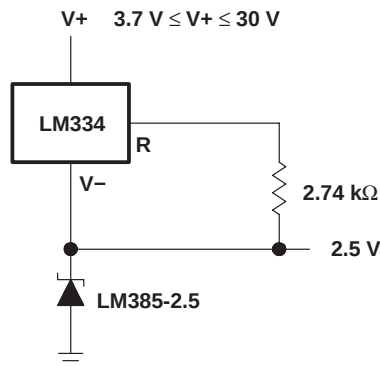


Figure 11. Operation Over a Wide Supply Range

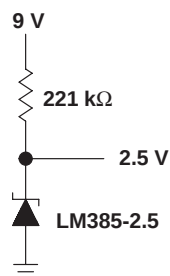


Figure 12. Reference From a 9-V Battery

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM285D-2-5	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	285-25	Samples
LM285DG4-2-5	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	285-25	Samples
LM285DR-2-5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	285-25	Samples
LM285DRG4-2-5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	285-25	Samples
LM285LP-2-5	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 85	285-25	Samples
LM285LPE3-2-5	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 85	285-25	Samples
LM285LPR-2-5	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 85	285-25	Samples
LM285LPRE3-2-5	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 85	285-25	Samples
LM385BD-2-5	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	385B25	Samples
LM385BDE4-2-5	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	385B25	Samples
LM385BDR-2-5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	385B25	Samples
LM385BDRE4-2-5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	385B25	Samples
LM385BLP-2-5	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	385B25	Samples
LM385BLPE3-2-5	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	385B25	Samples
LM385BLPR-2-5	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	385B25	Samples
LM385BPWR-2-5	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	385B25	Samples
LM385D-2-5	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	385-25	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM385DR-2-5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	385-25	Samples
LM385DRG4-2-5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	385-25	Samples
LM385LP-2-5	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	385-25	Samples
LM385LPE3-2-5	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	385-25	Samples
LM385LPR-2-5	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	385-25	Samples
LM385PWR-2-5	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	385-25	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM285DR-2-5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM385BDR-2-5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM385BPWR-2-5	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM385DR-2-5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM385PWR-2-5	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

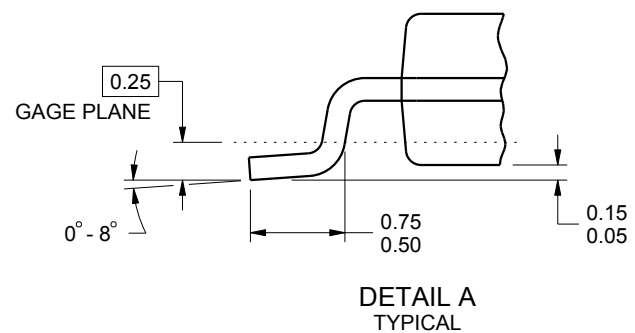
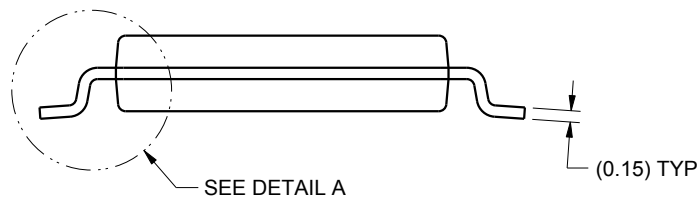
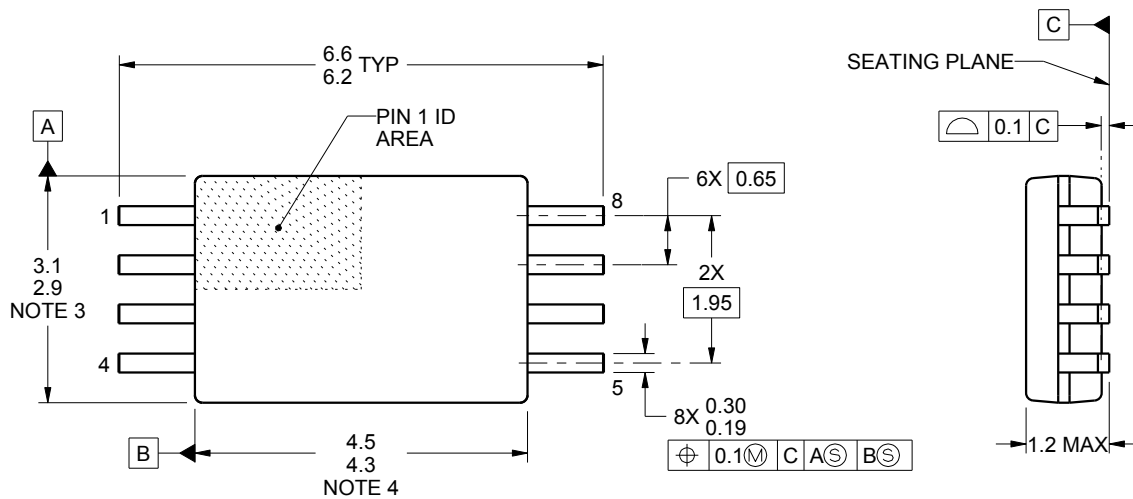
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM285DR-2-5	SOIC	D	8	2500	340.5	338.1	20.6
LM385BDR-2-5	SOIC	D	8	2500	340.5	338.1	20.6
LM385BPWR-2-5	TSSOP	PW	8	2000	367.0	367.0	35.0
LM385DR-2-5	SOIC	D	8	2500	340.5	338.1	20.6
LM385PWR-2-5	TSSOP	PW	8	2000	367.0	367.0	35.0

PW0008A

PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4221848/A 02/2015

NOTES:

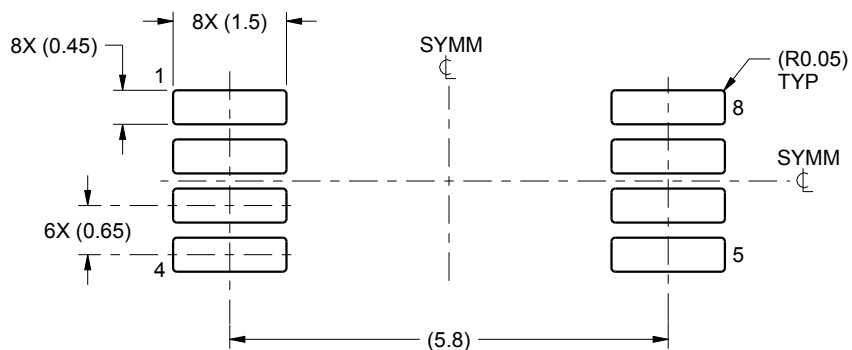
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153, variation AA.

EXAMPLE BOARD LAYOUT

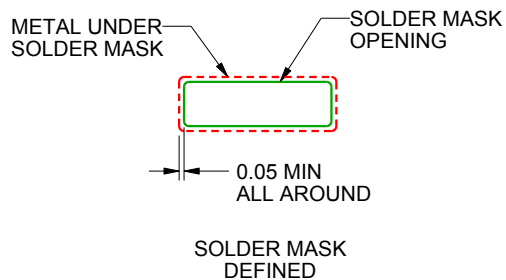
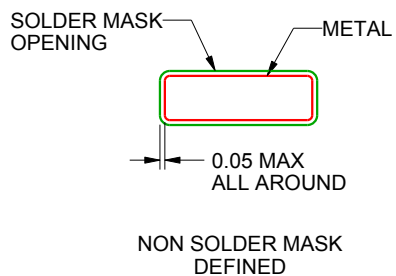
PW0008A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:10X



SOLDER MASK DETAILS
NOT TO SCALE

4221848/A 02/2015

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

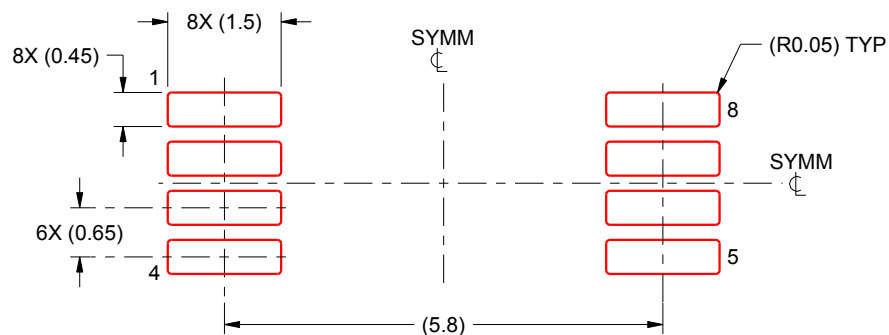
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0008A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:10X

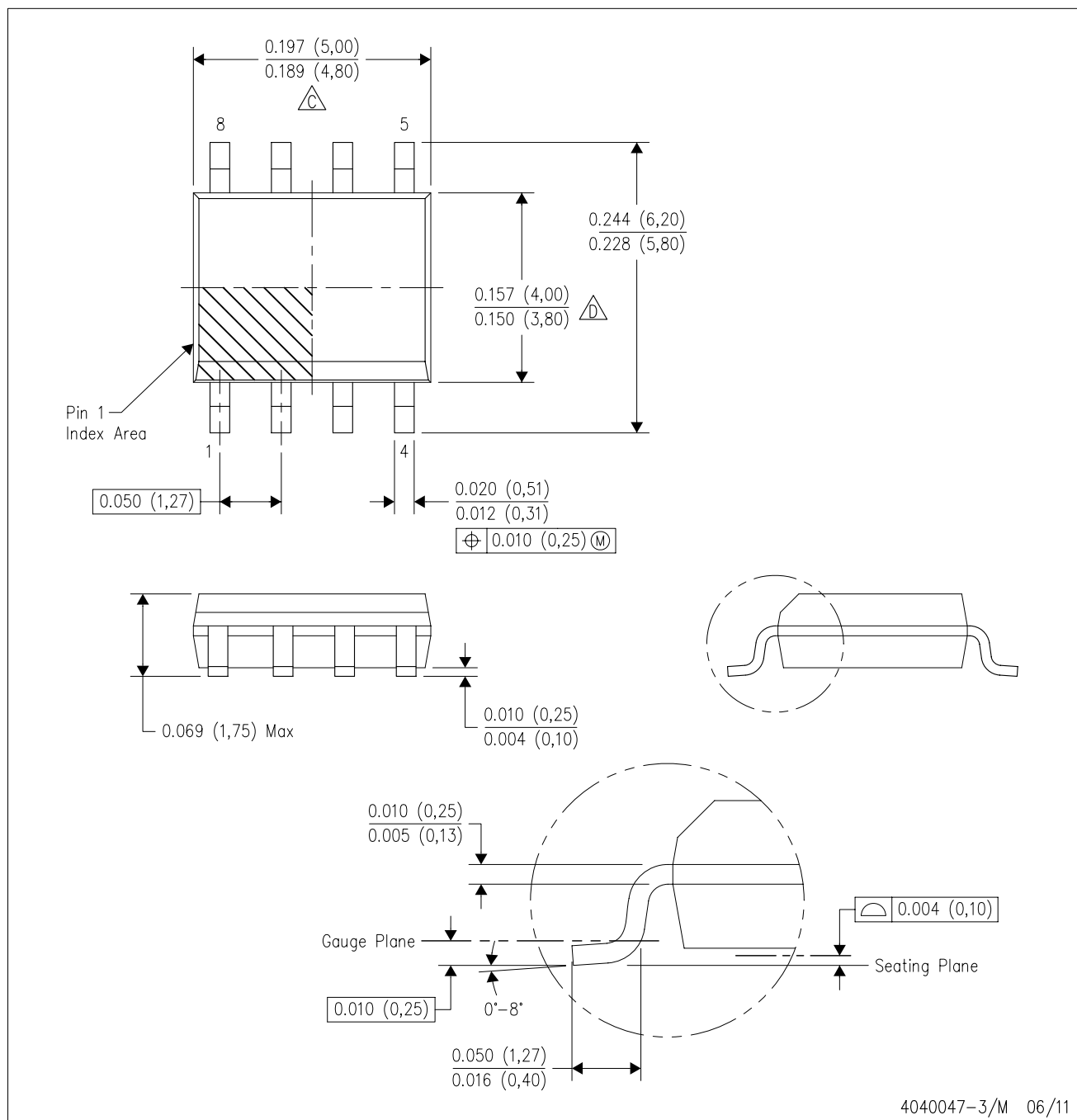
4221848/A 02/2015

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

D (R-PDSO-G8)

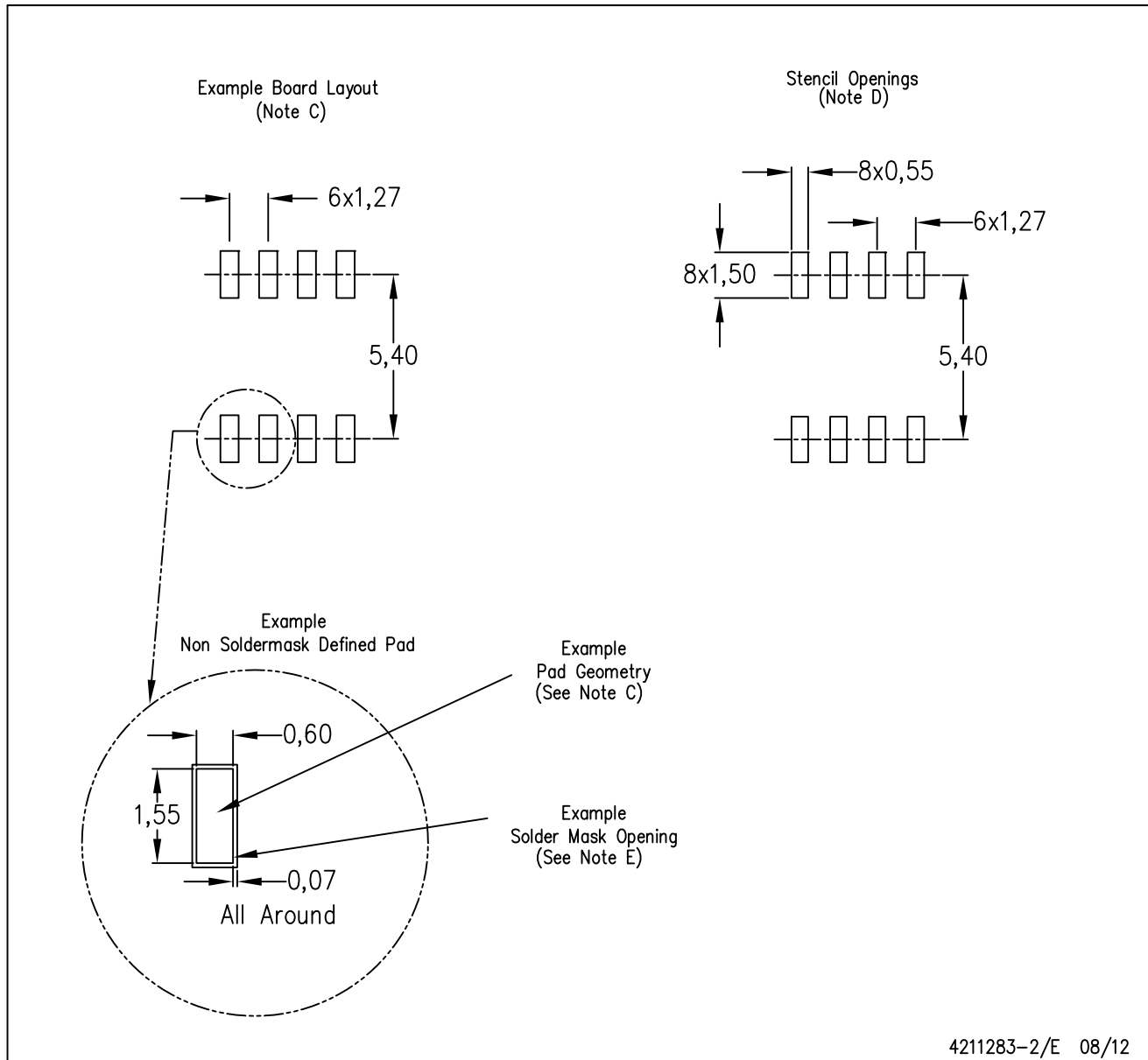
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AA.

D (R-PDSO-G8)

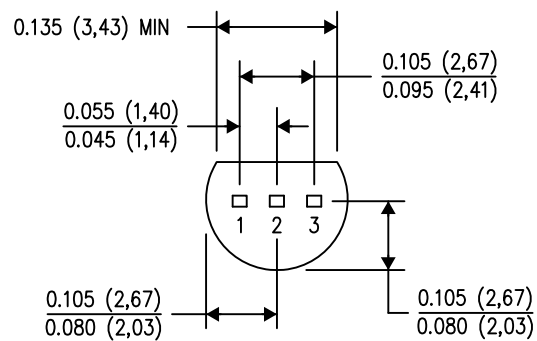
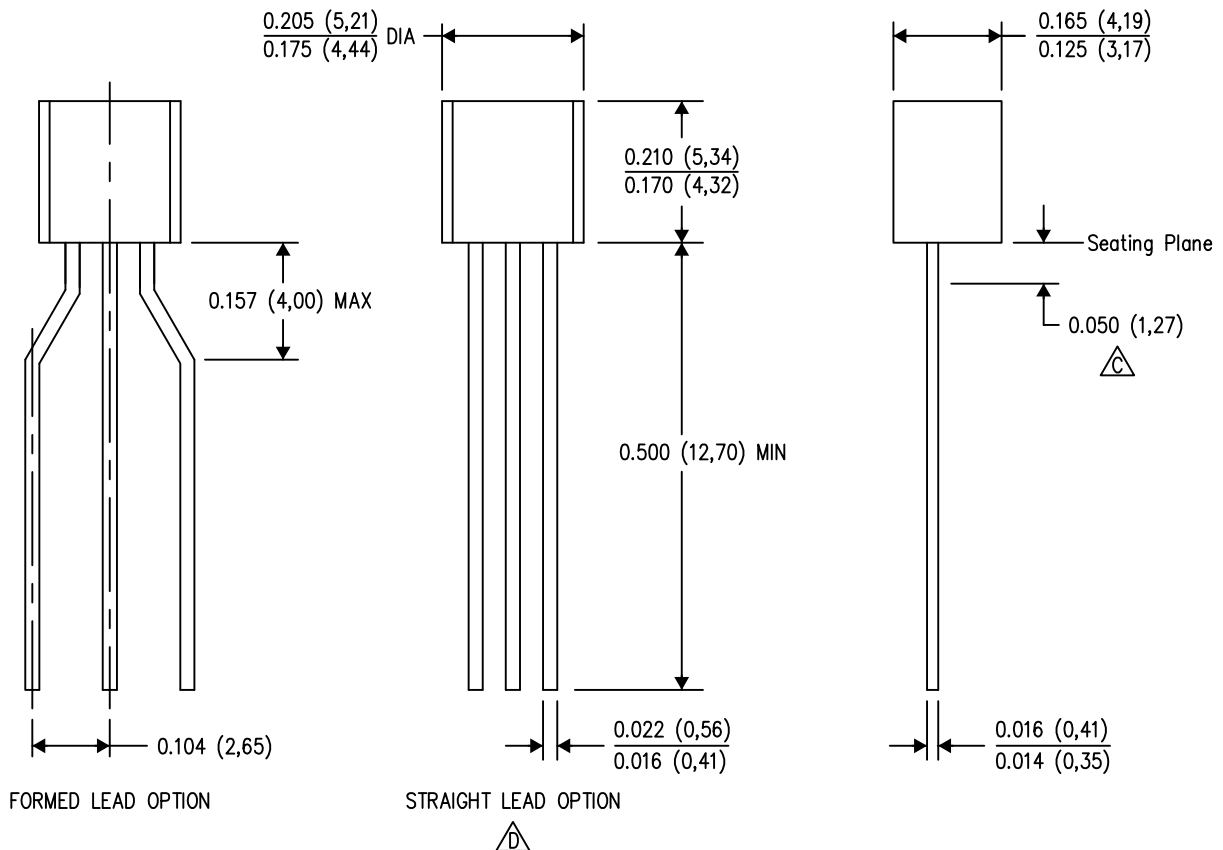
PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

LP (O-PBCY-W3)

PLASTIC CYLINDRICAL PACKAGE



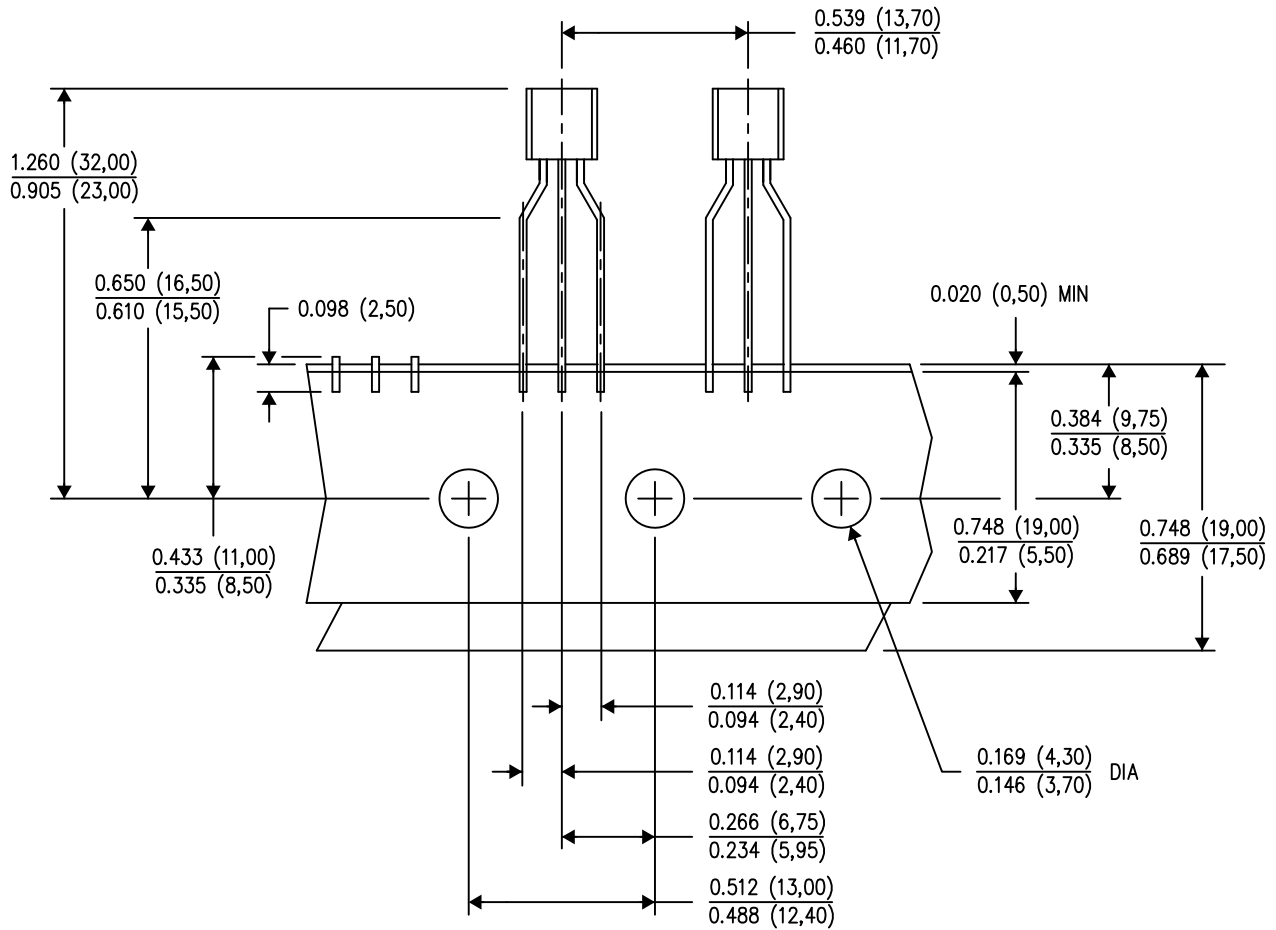
4040001-2/E 08/13

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Lead dimensions are not controlled within this area.
 - D. Falls within JEDEC TO-226 Variation AA (TO-226 replaces TO-92).
 - E. Shipping Method:
 Straight lead option available in bulk pack only.
 Formed lead option available in tape & reel or ammo pack.
 Specific products can be offered in limited combinations of shipping mediums and lead options.
 Consult product folder for more information on available options.

MECHANICAL DATA

LP (0-PBCY-W3)

PLASTIC CYLINDRICAL PACKAGE



TAPE & REEL

4040001-3/E 08/13

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Tape and Reel information for the Formed Lead Option package.

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